

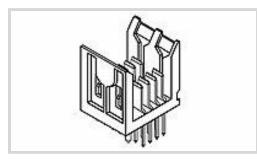
Z-PACK | Z-PACK Future Bus+

TE Internal #: 5536623-1 PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2 mm [. 079 in] Centerline, Partially Shrouded, Gold (Au), Z-PACK Future Bus+

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 4

Features

Product Type Features

Mixed & Hybrid Header	No
Connector Shape	Rectangular
PCB Connector Type	PCB Mount Header

Connector System	Board-to-Board	
Header Type	Partially Shrouded	
Sealable	No	
Connector & Contact Terminates To	Printed Circuit Board	
Connector Product Type	Connector Assembly	
Configuration Features		
Number of Loaded Positions	8	
Number of Power Positions	8	
Connector Contact Load Condition	Fully Loaded	
PCB Mount Orientation	Vertical	
Number of Positions	8	
Number of Rows	4	
Electrical Characteristics		
Operating Voltage	30 VDC	
Insulation Resistance	5000 MΩ	

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Contact Resistance	10 mΩ	
Body Features		
Primary Product Color	Natural	
Contact Features		
Contact Underplating Material	Nickel	
Contact Underplating Material Thickness	1.27 – 2.54 μm[50 – 100 μin]	
PCB Contact Termination Area Plating Material Finish	Matte	
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]	
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]	
Contact Layout	Matrix	
Contact Mating Area Length	8 mm[.315 in]	
Contact Base Material	Phosphor Bronze	
PCB Contact Termination Area Plating Material	Tin	
Contact Mating Area Plating Material	Gold (Au)	
Contact Type	Pin	
Contact Current Rating (Max)	3 A	

Termination Features

Termination Post & Tail Length	4.25 mm[.167 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Panel Mount Feature	Without
Mating Retention Type	Detent Lock
Mating Retention	With
Mating Alignment Type	Polarizing Rib
PCB Mount Alignment Type	Locating Posts
PCB Mount Retention	Without
PCB Mount Alignment	With
Connector Mounting Type	Board Mount
Mating Alignment	With
Housing Features	
Mating Entry Location	Тор
Housing Material	LCP

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04/14/2025 02:04PM | Page 2

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Centerline (Pitch)	2 mm[.079 in]
Dimensions	
Row-to-Row Spacing	2 mm[.079 in]
Connector Width	15.8 mm[.622 in]
PCB Thickness (Recommended)	1.6 mm[.063 in]
Connector Height	17 mm[.668 in]
Connector Length	11.88 mm[.486 in]
Jsage Conditions	
Operating Temperature (Max)	125 °C[257 °F]
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
Operation/Application	
Circuit Application	Power
ndustry Standards	
Glow Wire Rating	Standard Part - Not Glow Wire
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	48

Packaging Method

Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

Product Compliance Disclaimer

EU RoHS Directive 2011/65/EU	Compliant	
EU ELV Directive 2000/53/EC	Compliant	
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold	
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC	
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free	
Solder Process Capability	Pin-in-Paste capable to 260°C	

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Z-PACK Future Bus+

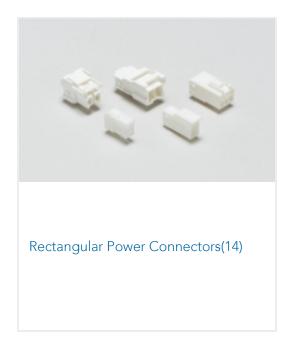








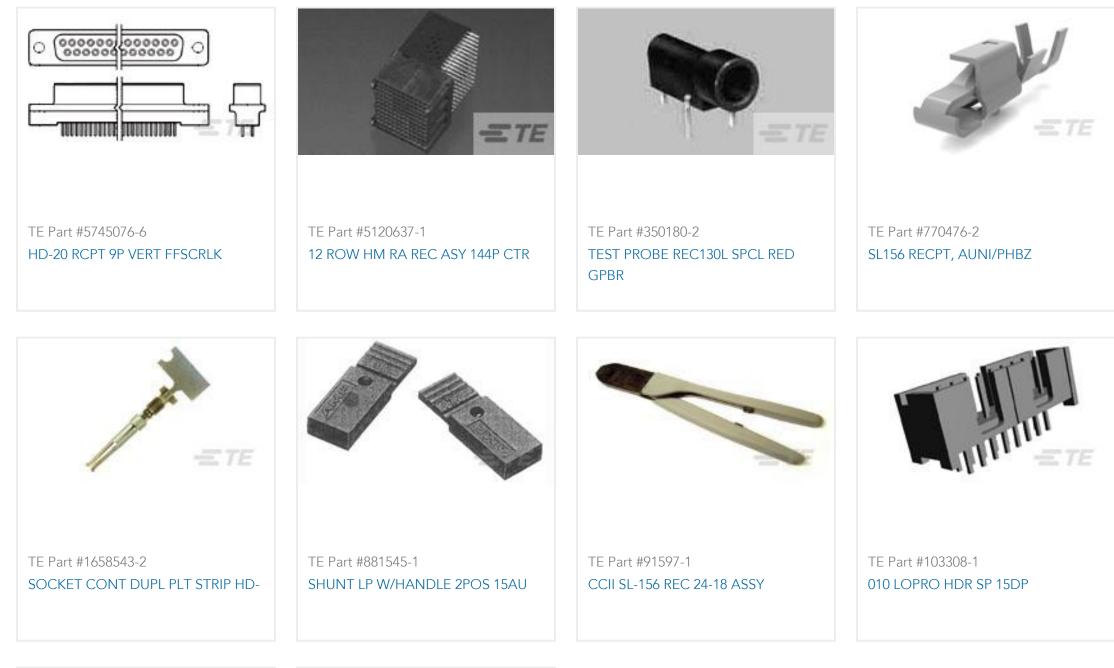
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Backplane Connector Housings(19)	Board-to-Board Headers & Receptacles(14)	Hard Metric Backplane Connectors(1)	PCB Headers & Receptacles(14)



Customers Also Bought

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2 mm [.079 in] Centerline, Partially Shrouded, Gold (Au), Z-PACK Future Bus+







TE Part #1934301-1 TinMan header Assy 3x8 Right



TE Part #58614-1 PROCRIMP, HT&D SL156

Documents

Product Drawings 2MMFB,ASY,008,PWR,HDR,SL,4.25

English

CAD Files Customer View Model ENG_CVM_5536623-1_O.3d_igs.zip English Customer View Model ENG_CVM_5536623-1_O.3d_stp.zip English Customer View Model ENG_CVM_5536623-1_O.2d_dxf.zip English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

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POWER_CONNECTORS_CATALOG_SEC01_BOARD_TO_BOARD

English

Product Specifications Application Specification

English